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Notice of Allowability	Application No.	Applicant(s)	
	10/629,055	KEVER, WAYNE	
	Examiner	Art Unit	
	Nema O. Berezny	2813	
The MAILING DATE of this communication appears on the cover sheet with the correspondence address All claims being allowable, PROSECUTION ON THE MERITS IS (OR REMAINS) CLOSED in this application. If not included herewith (or previously mailed), a Notice of Allowance (PTOL-85) or other appropriate communication will be mailed in due course. THIS NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT RIGHTS. This application is subject to withdrawal from issue at the initiative of the Office or upon petition by the applicant. See 37 CFR 1.313 and MPEP 1308.			
1. This communication is responsive to <u>Amendment, filed 2-16-05</u> .			
2. \boxtimes The allowed claim(s) is/are <u>23-33</u> .			
3. $igotimes$ The drawings filed on <u>29 July 2003</u> are accepted by the Ex	raminer.		
 4. Acknowledgment is made of a claim for foreign priority ur a) All b) Some* c) None of the: 1. Certified copies of the priority documents have 2. Certified copies of the priority documents have 3. Copies of the certified copies of the priority documents 	e been received. e been received in Application No.		on from the
International Bureau (PCT Rule 17.2(a)).			
* Certified copies not received:			
Applicant has THREE MONTHS FROM THE "MAILING DATE" noted below. Failure to timely comply will result in ABANDONN THIS THREE-MONTH PERIOD IS NOT EXTENDABLE.		y complying with the requ	uirements
5. A SUBSTITUTE OATH OR DECLARATION must be submitted. Note the attached EXAMINER'S AMENDMENT or NOTICE OF INFORMAL PATENT APPLICATION (PTO-152) which gives reason(s) why the oath or declaration is deficient.			
6. CORRECTED DRAWINGS (as "replacement sheets") must be submitted.			
(a) including changes required by the Notice of Draftspers		D-948) attached	
1) hereto or 2) to Paper No./Mail Date			
(b) including changes required by the attached Examiner's Paper No./Mail Date		·	
Identifying indicia such as the application number (see 37 CFR 1.84(c)) should be written on the drawings in the front (not the back) of each sheet. Replacement sheet(s) should be labeled as such in the header according to 37 CFR 1.121(d).			
7. DEPOSIT OF and/or INFORMATION about the deposit of BIOLOGICAL MATERIAL must be submitted. Note the attached Examiner's comment regarding REQUIREMENT FOR THE DEPOSIT OF BIOLOGICAL MATERIAL.			
Attachment(s) 1. ☑ Notice of References Cited (PTO-892) 2. ☑ Notice of Draftperson's Patent Drawing Review (PTO-948)	6. ☐ Interview Summar Paper No./Mail D	 5. Notice of Informal Patent Application (PTO-152) 6. Interview Summary (PTO-413), Paper No./Mail Date 	-152)
 Information Disclosure Statements (PTO-1449 or PTO/SB/C Paper No./Mail Date 	osure Statements (PTO-1449 or PTO/SB/08), 7. Texaminer's Amendment/Comment		
Examiner's Comment Regarding Requirement for Deposit of Biological Material	9.	CAPL WHITEHEAD, JR. TECHNOLOGY CENTER 2	AINER

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DETAILED ACTION

This Office Action is in response to Applicant's Amendment filed 2-16-05, which has been entered and considered. Claims 23-33 are currently pending.

Claim Rejections - 35 USC § 112

The rejection of claims 23-33 under 35 USC 112, second paragraph, made in prior Office Action is hereby withdrawn, subsequent to amendment made by Applicant in paper filed 2-16-05.

Allowable Subject Matter

The following is an examiner's statement of reasons for allowance of claims 23-33:

The prior art of record does not teach or disclose or make obvious an integrated circuit device, comprising inter alia: an IC die having a plurality of solder pads and a plurality of blocks of circuitry, a substrate with a corresponding plurality of solder pads, and a plurality of solder bumps connecting said substrate to said die in at least one configured electrical connection, wherein at least one of the blocks of circuitry is also configured to have at least one missing solder bump.

Eldridge et al. (2001/0052786) discloses a very similar device, except the pads with missing solder bumps are test pads and were never configured to make an electrical connection between the device and the substrate (Eldridge - paragraphs 47-51).

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Bhagath et al. (6,229,219) discloses a similar device (Fig.3), except the solder pads with missing solder bumps exist on the substrate instead of the die. The substrate is used to connect with more than one solder pad pattern, and therefore has additional unused pads (Abstract).

Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Nema O. Berezny whose telephone number is (571) 272-1686. The examiner can normally be reached on M-F 9-5:30.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Carl Whitehead, Jr. can be reached on (571) 272-1702. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

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Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

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